

High Performance, Resin-Blocking, Release Film



PACO•VIA RESIN-BLOCKING SYSTEM For the Lamination of Blind and Buried Via Holes

The **PACO•VIA**® Two-Component System (PACO•VIA and PACOPADS) is a performance-driven line of High-Temperature, Resin-Blocking Release Films. The **PACO•VIA** System is specifically engineered to enhance sequential lamination of Buried and Blind Via designed rigid printed Circuit Boards.

LAMINATION PROCESS ADVANTAGES

■ **Resin Containment**

PACO•VIA Resin Blocking Film contains the resin within the via barrel eliminating the need for secondary processing to remove cured resin from the panel surface.

■ **Barrel Fill**

PACO•VIA Resin Blocking Film allows the liquid resin to essentially fill the via Barrel.

■ **Contain Resin Squeeze-out**

PACO•VIA contains resin squeeze-out like traditional release films while offering superior copper surface buffering from damaged Separator Plates.

■ **Equalization of Pressure Throughout the Pressure Load**

The PACOPADS component of the PACO•VIA System ensures complete barrel fill, and controlled Dielectric Thickness. The PACOPADS eliminate air voids, inner-layer slippage and white corners or edges. PACOPADS also reduce image and glass cloth Transfer, and alleviate the potential of low-pressure prepreg Blisters. See PACOPADS Product Information Bulletin.

PACO•VIA SYSTEM FEATURES

- Three engineered Grades to fit all sequential lamination demands.
- Choice of PACOPADS Pressure Equalizing Press Pads designed to suit all lamination process parameters.
- Operating temperature of 425°F / 218°C for up to 4 hours.
- Proven worldwide performance since 1996.

- Essentially inert, no out-gassing, plate residue, interlaminar adhesion influence, no vacuum system contamination.
- Environmentally friendly: no chrome-depleting Chemicals, no Fluorines.

WIDE PROCESS WINDOW

- The PACO•VIA System is designed to contain the resin flow within Blind Via Holes (onto adjacent copper-carrying layers) and to fill buried Via Barrels, under a wide range of Lamination Pressures (175-350 psi/12-24 kg/cm²), Hole Diameters (.004 to .040"/0.1 to 1.0mm), Heat Rises and Prepreg types.
- The PACO•VIA System performs effectively well in Hydraulic and Hydraulic Vacuum-assist as well as with both stainless steel, and aluminum Separator Plates. Steel is preferred.
- The PACO•VIA System is suitable for all resin system types when laminated within the listed temperature constraints.

See PACOTHANE TECHNOLOGIES Lay-up Product Information Bulletin.

AVAILABILITY

The PACO•VIA System components are available in rolls and custom-sized sheet sizes, tooled to customers' specifications.

PACO•VIA, as well as the complete line of Lamination Enhancement Products listed below is available from leading local distributors around the world who offer "just-in-time" delivery from locally available stocks.

RELEASE PRODUCTS



PRESS PADS AND CONFORMABLES



APPLICATION SPECIFIC



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